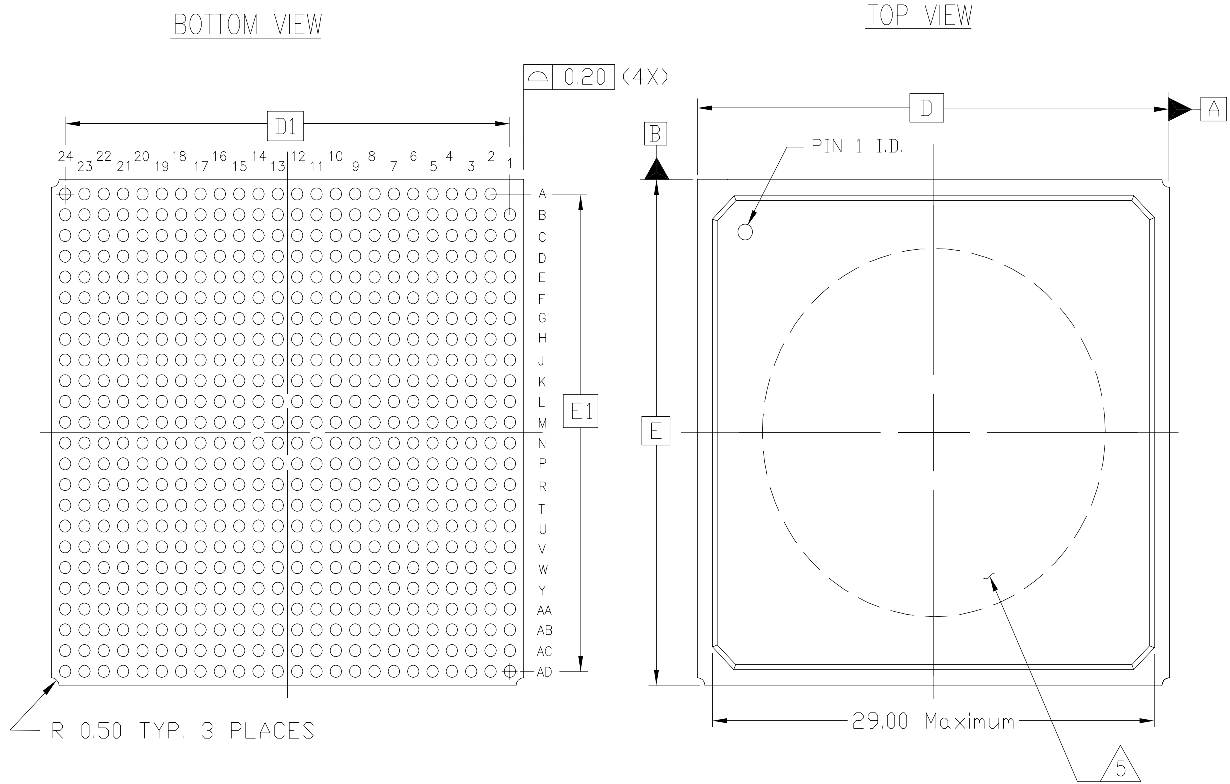
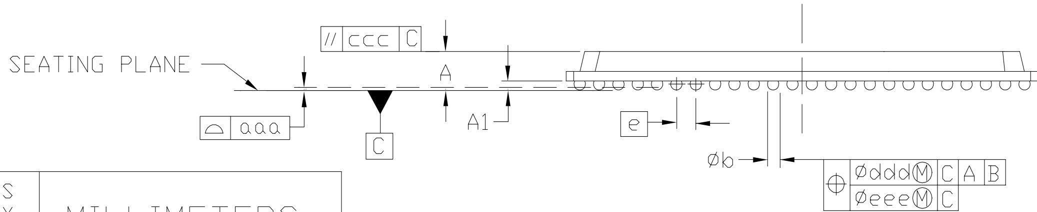
# Molded BGA (BG575/BGG575) Package




| SYMBOL | MILLIMETERS | | |
|---|---|---|---|
| | MIN. | NOM. | MAX. |
| A | – | 2.33 | 2.60 |
| $A_1$ | 0.50 | 0.60 | 0.70 |
| D/E | 31.00 BSC | | |
| $D_1/E_1$ | 29.21 REF | | |
| e | 1.27BSC | | |
| Øb | 0.60 | 0.75 | 0.90 |
| aaa | – | – | 0.20 |
| ccc | – | – | 0.35 |
| ddd | – | – | 0.30 |
| eee | – | – | 0.15 |
| M | 24 | | |

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–BAN–1 (DEPOPULATED)
4. NO SOLDER BALL AND LAND ON A1.
5. (5) HEAT SINK OPTION

575-BALL MOLDED BGA, 1.27MM PITCH (BG575/BGG575)

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